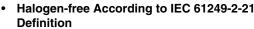


Vishay Siliconix

# N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
20	0.396 at V <sub>GS</sub> = 4.5 V	0.5			
	0.456 at V <sub>GS</sub> = 2.5 V	0.2	0.75		
	0.546 at V <sub>GS</sub> = 1.8 V	0.2	0.75		
	1.100 at V <sub>GS</sub> = 1.5 V	0.05			

#### **FEATURES**





100 % R<sub>g</sub> Tested

Gate-Source ESD Protected: 1000 V

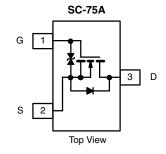
Compliant to RoHS Directive 2002/95/EC

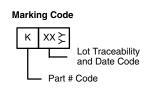


HALOGEN **FREE** 

#### **APPLICATIONS**

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays,
- **Battery Operated Systems**
- **Power Supply Converter Circuits**





Ordering Information: Si1012CR-T1-GE3 (Lead (Pb)-free and Halogen-free)

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	$V_{DS}$	20	V		
Gate-Source Voltage		$V_{GS}$	± 8	7	
Continuous Drain Current /T 150 °C\8	T <sub>A</sub> = 25 °C	1 1_	0.63 <sup>a, b</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		0.5 <sup>a, b</sup>	Α	
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	2			
Continuous Source-Drain Diode Current T <sub>A</sub> = 25 °C		I <sub>S</sub>	0.2 <sup>a, b</sup>	Α	
Marrian Danier Dissination	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.24 <sup>a, b</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	] 'D	0.15 <sup>a, b</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian de Ambient	t ≤ 5 s	$R_{thJA}$	440	530	°C/W
Maximum Junction-to-Ambient <sup>D</sup>	Steady State		540	650	C/VV

a. Surface mounted on 1" x 1" FR4 board.

b. t = 5 s.

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<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	ne/Tu		17		m\//°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 1.8		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.4		1	V	
Cata Caura I aslessa	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 30		
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	1	
Zoro Cata Valtaga Drain Current	1	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.6 \text{ A}$		0.330	0.396		
	D	$V_{GS} = 2.5 \text{ V}, I_D = 0.3 \text{ A}$		0.380	0.456	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 1.8 \text{ V}, I_D = 0.3 \text{ A}$		0.420	0.546		
	·	$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$		0.720	1.100		
Forward Transconductance	9 <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		7.5		S	
Dynamic <sup>b</sup>					l		
Input Capacitance	C <sub>iss</sub>			43		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		14			
Reverse Transfer Capacitance	C <sub>rss</sub>			8			
Total Oaks Observe	Q <sub>g</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 0.6 \text{ A}$		1.3	2		
Total Gate Charge				0.75	1.2	nC	
Gate-Source Charge	Q <sub>qs</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.6 \text{ A}$		0.15			
Gate-Drain Charge	Q <sub>gd</sub>			0.13			
Gate Resistance	$R_{g}$	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			11	20		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 20 $\Omega$		16	24		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		26	39	ns	
Fall Time	t <sub>f</sub>	_		11	20		
<b>Drain-Source Body Diode Characterist</b>	ics						
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				2	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 0.5 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			10	15	nC	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 0 5 4 41/44 400 4/4-		2	4		
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = 0.5 A, dI/dt = 100 A/μs		5		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			5		1 !	

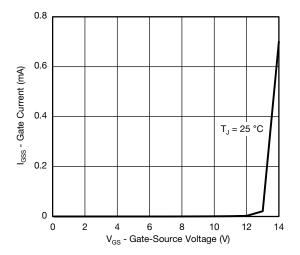
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

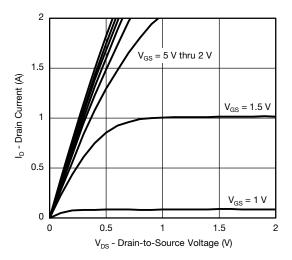
b. Guaranteed by design, not subject to production testing.



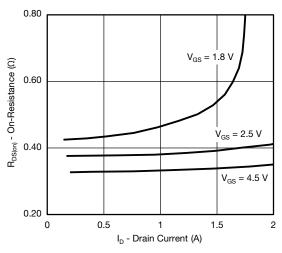
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



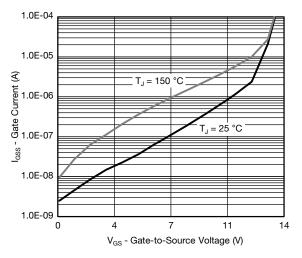
#### Gate Current vs. Gate-Source Voltage



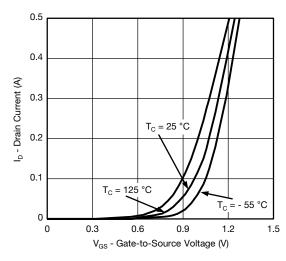
#### **Output Characteristics**



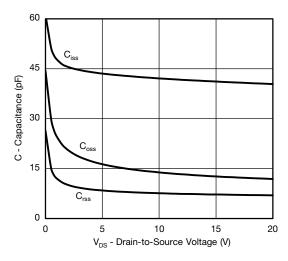
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



Transfer Characteristics

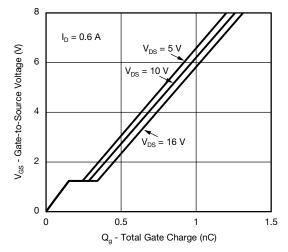


Capacitance

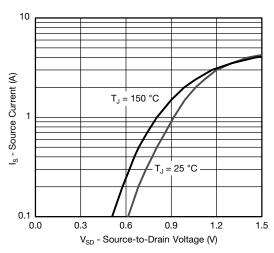
# Vishay Siliconix

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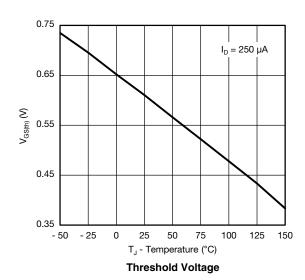
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

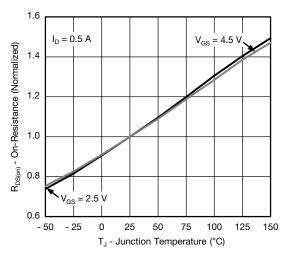


#### **Gate Charge**

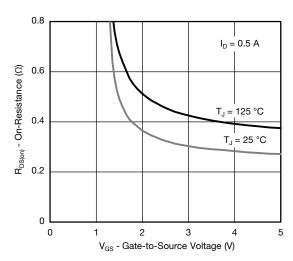


#### Soure-Drain Diode Forward Voltage

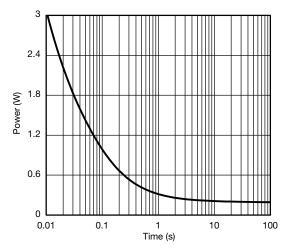




On-Resistance vs. Junction Temperature



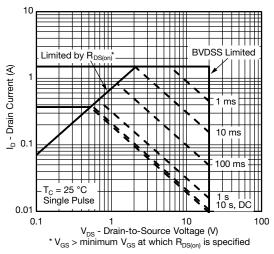
On-Resistance vs. Gate-to-Source Voltage



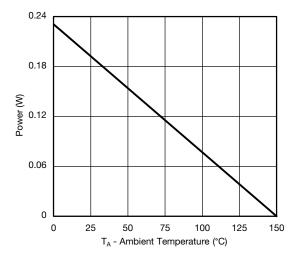
Single Pulse Power, Junction-to-Ambient



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

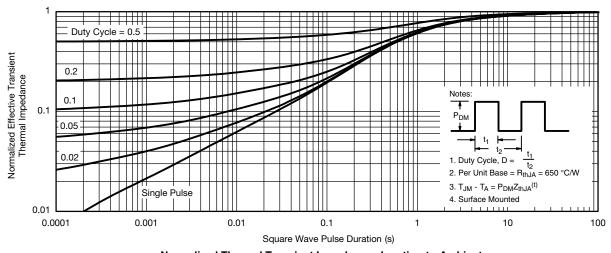






Power Derating, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



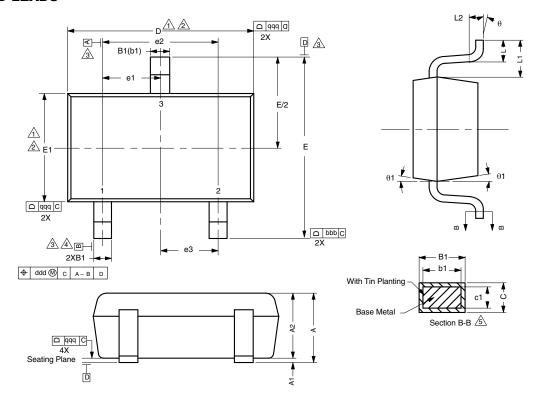
Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67519.

Document Number: 67519 S11-2238-Rev. B, 14-Nov-11



#### **SC-75A: 3-LEADS**



#### **Notes**

Dimensions in millimeters will govern.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interelead flash, but including any mismatch between the top and bottom of the plastic body.

2\Datums A, B and D to be determined 0.10 mm from the lead tip.

4 Terminal positions are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES
aaa	0.10
bbb	0.10
ccc	0.10
ddd	0.10

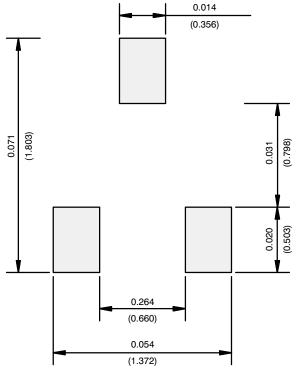
DIM.	MIN.	NOM.	MAX.	NOTE
Α	-	-	0.80	
A <sub>1</sub>	0.00	-	0.10	
A <sub>2</sub>	0.65	0.70	0.80	
B <sub>1</sub>	0.19	-	0.24	5
b <sub>1</sub>	0.17	-	0.21	
С	0.13	-	0.15	5
C <sub>1</sub>	0.10	-	0.12	5
D	1.48	1.575	1.68	1, 2
E	1.50	1.60	1.70	
E <sub>1</sub>	0.66	0.76	0.86	1, 2
e <sub>1</sub>	0.50 BSC			
e <sub>2</sub>	1.00 BSC			
e <sub>3</sub>	0.50 BSC			
L	0.15	0.205	0.30	
L <sub>1</sub>	0.40 REF			
L <sub>2</sub>	0.15 BSC			
θ	0°	-	8°	
$\theta_1$	4°	-	10°	
ECN: E11-	2210-Rev. D,	08-Aug-11		

ECN: E11-2210-Rev. D, 08-Aug-11

DWG: 5868



#### **RECOMMENDED MINIMUM PADS FOR SC-75A: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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